

## OFFSHORE CAPABILITIES 2017

ENGINEERING	MANUFACTURING	CAPABILITY
Laminate	Type	FR4(170°-220°),Aluminum base,Rogers,Halogen Free,CEM-3,FR5,PTFE,Getek,BT,Polyimide FR4 (Dciyfree),Thermal Prepreg,buried capacitance
	Thickness	0.2~5.0mm
	Board Thickness Tolerance	+/-10%(3.2mm: +/-0.25mm)
Production Type	Surface Treatment	HAL,HAL LF,OSP,gold plating, Immersion Gold,Immersion Silver,Immersion Tin,Gold Finger
	Layer Counts	1-50L
Cut Lamination	Working Panel Size	580*800 mm
Inner Layer	Inner Core Thickness	0.1~2.0mm
	Conductor Width/Spacing	Min: 3/3mil
Drilling	Holes Diameter	Min: 0.15mm
	Laser Holes	Min: 0.10mm
	Hole Dia Tolerance	NPTH:+/-0.05mm PTH:+/-0.075mm
PHT+Panel Plating	Hole Wall Copper Thickness	>=20um
	Uniformity	>=90%
	Aspect Ratio	10:01
Outer Layer	Conductor Width	Min: 3.0mil
	Conductor Spacing	Min: 3.0mil
Pattern Plating	Finished Copper Thickness	1oz~12oz
ENIG/Flash Gold	Nickel Thickness	>=120u"
	Gold Thickness	1~5u"
Solder Mask	Thickness	15~35um
	Solder Mask Bridage	3mil
	Plug Hole Dia	0.3~0.6mm
Legend	Line Width/Line Spacing	4/4mil
Gold Finger	Nickel Thickness	>=120u"
	Gold Thickness	1~50u"
Hot Air Level	Tin Thickness	100-300u"
OSP	Membrane Thickness	0.2-0.4um
Routing	Tolerance of Dimension	+/-0.1mm

	Slot Size	Min.0.8mm
	Cutter Diameter	0.8mm-2.4mm
Punching	Outline Tolerance	+/-0.05mm
	Slot Size	Min.0.7mm
V-Cut	V-Cut Dimension	Min. 60mm
	Angle	15° 30° 45°
	Remain Thickness Tolerance	+/-0.1mm
Beveling	Beveling Dimension	30-300mm
Test	Testing Voltage	250V
	Max. Dimension	580x580mm
Impedance Control	Tolerance	(37.5~120) +/-10%
Peel Strength		1.4N/mm